

ROG FLEX CARD TERMINAL FCF SERIES

Specifications:

FCF HI-TEMP

Insulator Material:
Black Liquid Crystal Polymer
Terminal Material:
Phosphor Bronze
Operating Temp Range:
-65°C to +105°C with Tin;
-65°C to +125°C with Gold
Max Processing Temp:
230°C for 60 seconds
Plating:
Sn or Au over 50μ" (1,27μm) Ni

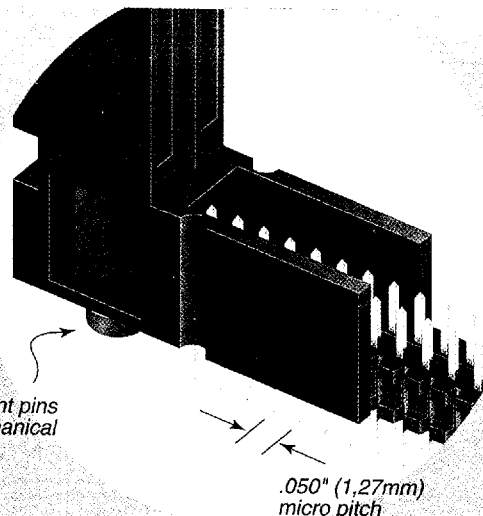
ROG FLEX
EMF

APPLICATIONS

NO OF PINS PER ROW	CARD WIDTH
50	(77,47) 3,050
40	(64,77) 2,550
30	(52,07) 2,050
20	(39,37) 1,550

APPLICATION SPECIFIC OPTION

Other pin counts and card widths available. Call Samtec.



Vertical or horizontal orientation

Note: Some lengths, styles and options are non-standard, non-returnable.



20, 30, 40 & 50
(Call Samtec for other sizes)

-L

= 10μ" (0,25μm)
Gold on post
75μ" (1,90μm)
Tin on tail

-S

= 30μ" (0,76μm)
Gold on post,
75μ" (1,90μm)
Tin on tail

TAIL OPTION

-RA
= Right Angle
(Leave blank for vertical versions)

